



Surge arrester

2-electrode arrester

Series/Type: S50-A90X
Ordering code: B88069X1913T902
Date: 2019-04-23
Version: 03

Product description

The S50-series has been especially designed to meet data transmission protection requirements. The optimized design features a high level of protection against fast rising transients usually caused by lightning disturbances. For use in high frequency data lines, the series offers ultra low capacitances and shows only marginally signal losses up to high frequencies. The devices are extremely reliable and are able to withstand high surge currents without destruction.

Features

- Small size (EIA 2220)
- Short response time
- High current capability
- Stable performance over service life
- Ultra low capacitance and insertion loss
- High insulation resistance
- Excellent SMD handling
- RoHS-compatible

Applications

Telecommunication:

- Ethernet, PoE, xDSL
- Cable modem, splitters, line cards
- Wireless antenna protection

Others:

- CCTV
- Switching power supply

Product characteristics

Physical dimensions (length x width x height)	0.22 x 0.20 x 0.20	in
	5.7 x 5.0 x 5.0	mm
	EIA 2220 / 5750 metric	
Weight	~ 0.3	g
Operating temperature	-40 ... +125	°C
Recommended storage ¹⁾ - temperature - humidity - period	+5 ... +35 45 ... 80 ≤ 2	°C % years
Climatic category (IEC 60068-1)	40/125/21	
Moisture sensitivity level ²⁾	1	
Marking	without	

Notes:

¹⁾ Specified in terms of corrosion against Sn-plating

²⁾ Tests according to JEDEC J-STD-020

Electrical specifications and stress test methods

Nominal DC spark-over voltage ^{3) 4)}	90	V
Tolerance	±20	%
Min.	72	V
Max.	108	V
Impulse spark-over voltage		
at 100 V/μs	- for 99% of measured values - typical values of distribution	< 550 < 500
at 1 kV/μs	- for 99% of measured values - typical values of distribution	< 600 < 550
Service life ^{5) 6)}		
10 operations	50 Hz, 1 s	5
1 operation	50 Hz, 0.18 s (9 cycles)	10
10 operations	8/20 μs	5
1 operation	8/20 μs ³⁾	10
1 operation	10/350 μs	0.5
300 operations	10/1000 μs	100
Insulation resistance at 50 V _{DC}	> 1	GΩ
Capacitance at 1 MHz	< 1	pF
Arc voltage at 1 A	~ 15	V
Glow to arc transition current	< 0.8	A
Glow voltage	~ 60	V

³⁾ At delivery AQL 0.65 level II, DIN ISO 2859

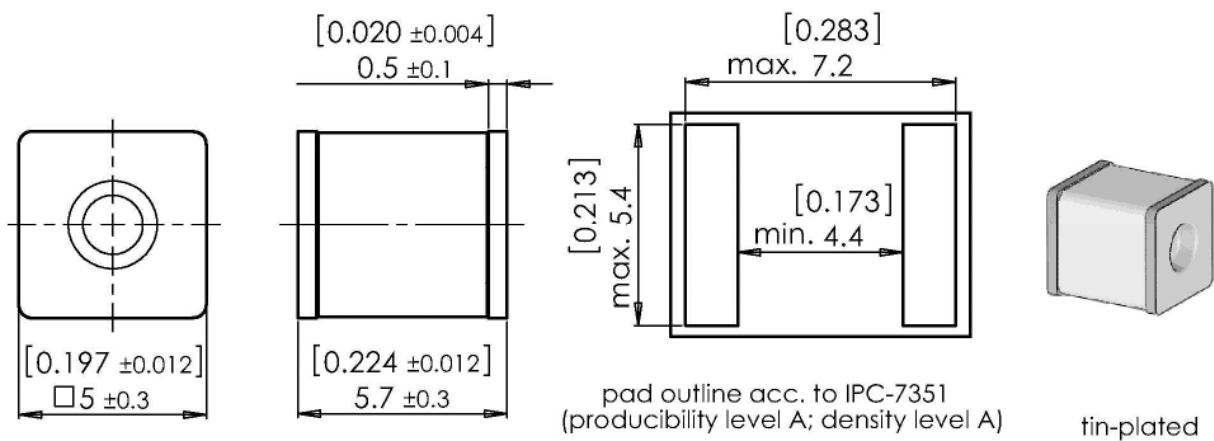
⁴⁾ In ionized mode

⁵⁾ Tests according to ITU-T Rec. K. 12 and UL 497B

⁶⁾ DC spark-over voltage values may exceed ±50% after stress, but tubes still operates w/o venting

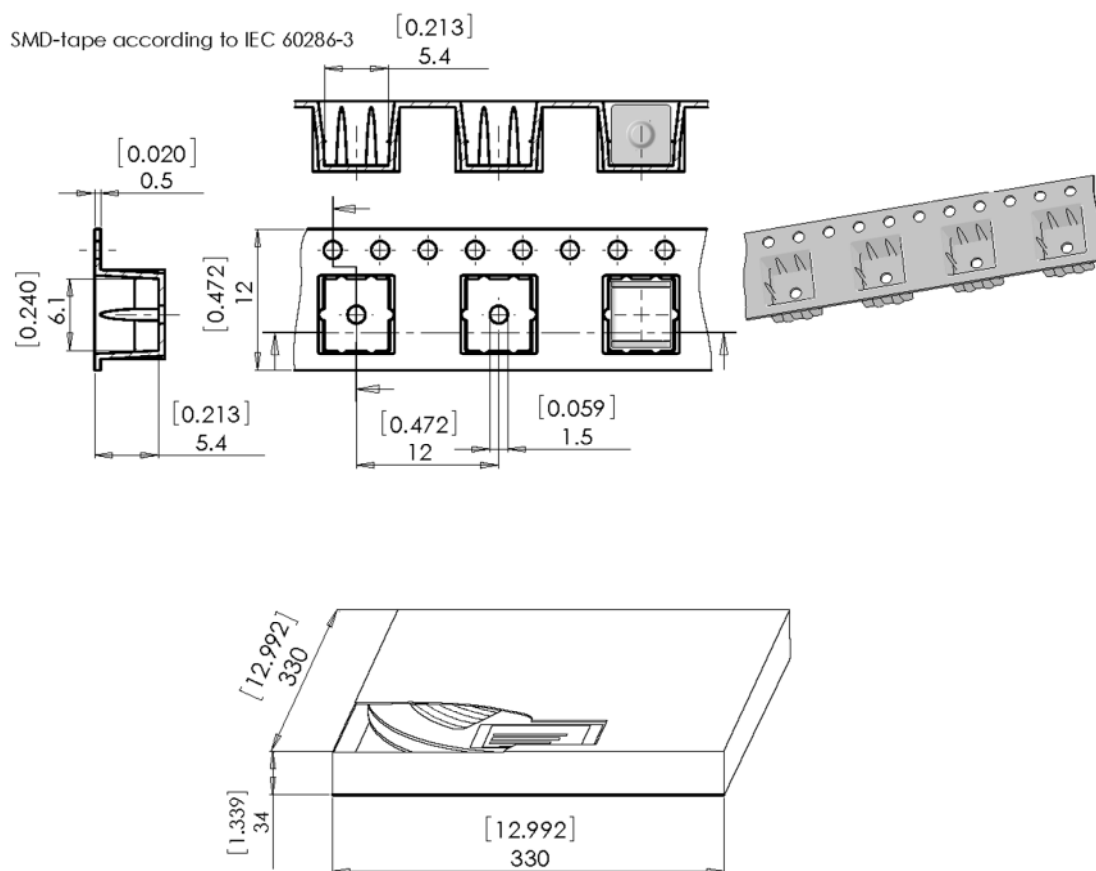
Terms and current waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21 and IEC 61643-311.

Dimensions in mm and inch [...]



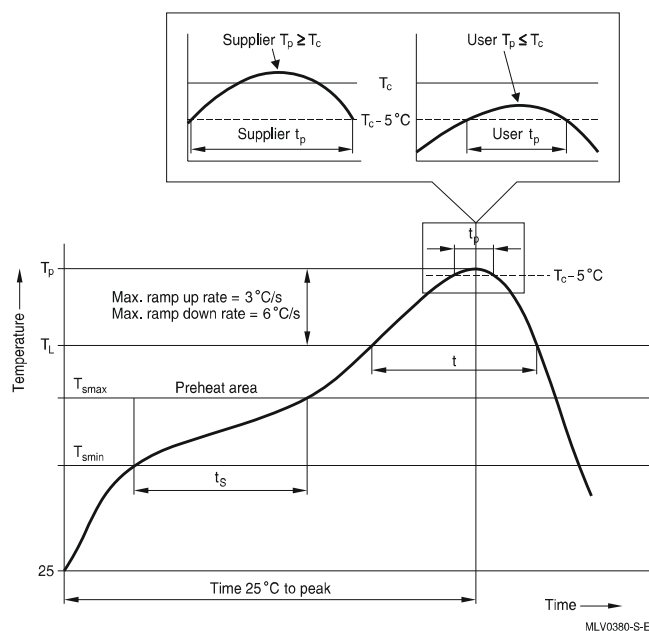
Ordering code and packing advice

B88069X1913T902 = 900 pcs. on SMD-tape



Soldering parameter

Reflow soldering



Reflow profile features		Sn- Pb eutectic assembly	Pb-free assembly
Preheat and soak - Temperature min - Temperature max - Time	T_{smin} T_{smax} t_{smin} to t_{smax}	100 °C 150 °C 60 ... 120 s	150 °C 200 °C 60 ... 180 s
Average ramp-up rate	T_{smax} to T_p	max. 3 °C/ s	max. 3 °C/ s
Liquidous temperature Time at liquidous	T_L t_L	183 °C 60 ... 150 s	217 °C 60 ... 150 s
Peak package body temperature *, Classification temperature **	T_p , T_c	220 ... 235 °C **	245 ... 260 °C **
Time (t_p) ** within 5 °C of the specified classification temperature (T_c)		20 s ***	30 s ***
Average ramp-down rate	T_p to T_{smax}	max. 6 °C/ s	max. 6 °C/ s
Time 25 °C to peak temperature		max. 6 min	max. 8 min

* = Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.
 ** = For details please refer to JEDEC J-STD-020D.
 *** = Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

Surface mounted components (SMD) may exhibit a temporary increase in the DC spark-over voltage after the solder reflow process. The components will recover within 24 hours. There is no quality defect nor change in protection levels during the temporary change in DC spark-over voltage.

Cautions and warnings

- Do not operate surge arresters in power supply networks, whose maximum operating voltage exceeds the minimum spark-over voltage of the surge arresters.
- Surge arresters may become hot in the event of longer periods of current stress (burn risk). In the event of overload the connectors may fail or the component may be destroyed.
- Surge arresters must be handled with care and must not be dropped.
- Do not continue to use damaged surge arresters.
- The shown SMD pad dimensions represent a safe way to mount the arrester and are a recommendation of the manufacturer. During the reflow process it must be assured that no solder material reduces the insulation distance between the pads below the arrester.
- SMD surge arresters should be soldered within 24 month after shipment.

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Important notes

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